IN THE CLAIMS

Please amend the claims as indicated in Attachment B. The following is a clean version of the entire set of pending claims.

1. A reel-deployable printed circuit board comprising:

an elongated, flexible base board having opposite edges and a slit formed into it, the slit having an inner periphery defining a unit board within the flexible base board; and,

at least a connection bar connecting the unit board to the base board such that the unit board is pivotable on the connection bar relative to the base board.

2. The circuit board of Claim 1, further comprising:

a bonding pad on a top surface of the unit board;

a contact on a bottom surface of the unit board; and,

a via hole through the unit board electrically connecting the bonding pad to the contact.

3. The circuit board of Claim 2, wherein the contact comprises a layer of copper plated with gold.

4. The circuit board of Claim 1, further comprising a dam inside the inner periphery of the slit.

5. The circuit board of Claim 1, wherein the base board is made of a glass-epoxy material.

6. The circuit board of Claim 1, wherein the base board includes a sprocket hole along at least one of the edges thereof.

7. The circuit board of Claim 1, wherein the base board includes a position hole along one of the edges thereof.

8. The circuit board of Claim 2, further comprising:

a semiconductor chip attached to an upper surface of the unit board, the chip having a connection pad on an upper surface thereof; and,

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SKJERVEN MORRILL
MACPHERSON LLP

25 METRO DRIVE
SUITE 700
SAN JOSE, CA 95110
(408) 453-9200
FAX (408) 453-7979

a conductive wire having opposite ends, each bonded to a respective one of the bonding pad on the unit board and the connection pad on the chip.

9. The circuit board of Claim 8, further comprising an encapsulant formed on the top surface of the unit board and encapsulating a region including the chip, the conductive wire, the bonding pad, and the connection pad.

10. (New) An apparatus comprising:

a flexible base board; and

a plurality of unit boards disposed within the flexible base board, the plurality of unit boards connected to the flexible base board by at least one connection bar, wherein each unit board is pivotable on its respective connection bar(s).

11. (New) The apparatus of Claim 10, further comprising:

bonding pads on a top surface of the unit boards;

contacts on a bottom surface of the unit boards; and

via holes through the unit boards electrically connecting the bonding pads to the contacts.

12. (New) The apparatus of Claim 11, wherein the contacts comprise a layer of copper plated with gold.

13. (New) The apparatus of Claim 10, further comprising dams disposed at the periphery of the unit boards.

14. (New) The apparatus of Claim 10, wherein the base board is made of a glass-epoxy material.

15. (New) The apparatus of Claim 10, wherein the base board includes a sprocket hole along at least an edge thereof.

16. (New) The apparatus of Claim 10, wherein the base board includes a position hole along an edge thereof.

17. (New) The apparatus of Claim 11, further comprising:

semiconductor chips attached to an upper surface of the unit boards, the chips having connection pads on an upper surface thereof; and

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25 METRO DRIVE
SUITE 700
SAN JOSE, CA 95110
(408) 453-9200
FAX (408) 453-7979

conductive wires having opposite ends, each bonded to a respective one of the bonding pads on the unit boards and the connection pads on the chips.

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18. (New) The apparatus of Claim 17, further comprising a protective cover formed on the top surfaces of the unit boards.

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19. (New) A reel-deployable printed circuit board comprising:

an elongated, flexible base board having opposite edges and a slit formed into it, the slit having an inner periphery defining a unit board within the flexible base board; and

one or more connection bars connecting the unit board to the base board such that the unit board is pivotable on the connection bar(s) relative to the base board, the connection bar(s) being disposed such that an axis of the connection bar(s) is perpendicular to a direction of movement of the reel-deployable printed circuit board.

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20. (New) The circuit board of Claim 19, further comprising:

a bonding pad on a top surface of the unit board;

a contact on a bottom surface of the unit board; and,

a via hole through the unit board electrically connecting the bonding pad to the contact.

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21. (New) The circuit board of Claim 20, wherein the contact comprises a layer of copper plated with gold.

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22. (New) The circuit board of Claim 19, further comprising a dam inside the inner periphery of the slit.

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23. (New) The circuit board of Claim 19, wherein the base board is made of a glass-epoxy material.

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24. (New) The circuit board of Claim 19, wherein the base board includes a sprocket hole along at least one of the edges thereof.

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25. (New) The circuit board of Claim 19, wherein the base board includes a position hole along one of the edges thereof.

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25 METRO DRIVE
SUITE 700
SAN JOSE, CA 95110
(408) 453-9200
FAX (408) 453-7979

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36. (New) The circuit board of Claim 30, further comprising:

a semiconductor chip attached to an upper surface of the unit board, the chip having a connection pad on an upper surface thereof; and,

a conductive wire having opposite ends, each bonded to a respective one of the bonding pad on the unit board and the connection pad on the chip.

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37. (New) The circuit board of Claim 36, further comprising an encapsulant formed on the top surface of the unit board and encapsulating a region including the chip, the conductive wire, the bonding pad, and the connection pad.

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MACPHERSON LLP

25 METRO DRIVE
SUITE 700
SAN JOSE, CA 95110
(408) 453-9200
FAX (408) 453-7979